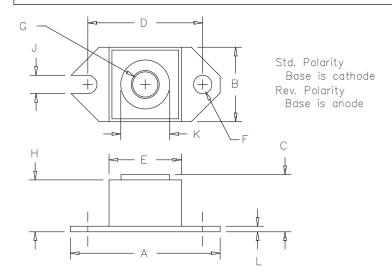
240 Amp Schottky Rectifier HS246150



| Dim. Inches | | | Millimeter | | |
|---------------------------------|---|---|---|---|-------------|
| | Minimum | Maximum | Minimum | Maximum | Notes |
| A B C D E F G | 1.52 .725 .605 1.182 .745 .152 | 1.56 .775 .625 1.192 .755 .160 | 38.61 18.42 15.37 30.02 18.92 3.86 UNC-2B | 39.62 19.69 15.88 30.28 19.18 4.06 | Sq. Dia. |
| H J K L | .525 .156 .495 .120 | .580 .160 .505 .130 | 13.34 3.96 12.57 3.05 | 14.73 4.06 12.83 3.30 | Dia. |

Microsemi Industry Working Peak Repetitive Peak Catalog Number Part Number Reverse Voltage Reverse Voltage HS246150* 249NQ150 150V 150V

*Add Suffix R for Reverse Polarity

- Schottky Barrier Rectifier
- Guard Ring Protection
- 240 Amperes 150 Volts
- 175°C Junction Temperature
- Reverse Energy Tested
- ROHS Compliant

Electrical Characteristics

Average forward current Maximum surge current Maximum repetitive reverse current Typical peak forward voltage Max peak forward voltage Typical peak reverse current Max peak reverse current Typical junction capacitance

F(AV) 240 Amps I FSM 3300 Amps R(OV) 2 Amps ٧FM 0.65 Volts V_{FM} 0.86 Volts $^{\rm I}$ RM 150mA $^{\rm I}$ RM 8.0mA

 $^{T}C = 118^{\circ}C$, Square wave, $^{R}\Theta JC = .24^{\circ}C/W$ 8.3ms, half sine, $^{\mathsf{T}}\mathsf{J} = 175^{\circ}\mathsf{C}$ f = 1 KHZ, 25 $^{\circ}\mathsf{C}$ |FM| = 240A: |TJ| = 175°C* 1 FM = 240A: 7 J = 25 $^{\circ}$ C*

VRRM, TJ = 125°C* VRRM, TJ = 25°C $VR = 5.0V, TC = 25^{\circ}C$

*Pulse test: Pulse width 300 usec, Duty cycle 2%

6000pF

Thermal and Mechanical Characteristics

Storage temp range Operating junction temp range Max thermal resistance Typical thermal resistance (greased) Terminal Torque Mounting Base Torque Weight

TSTG ΤĴ ROJC Recs

 C_{\cup}

-55°C to 175°C -55°C to 175°C 0.21°C/W Junction to case 0.12°C/W Case to sink 35-40 inch pounds 20-25 inch pounds 1.1 ounces (32 grams) typical



HS246150

Figure 1 Typical Forward Characteristics

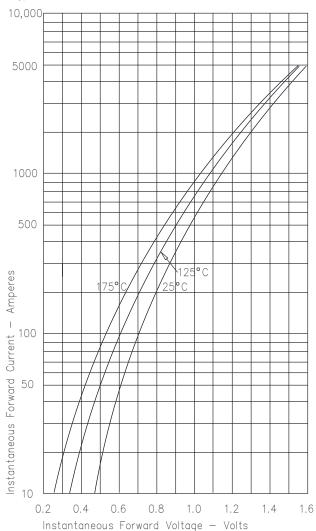


Figure 3 Typical Junction Capacitance

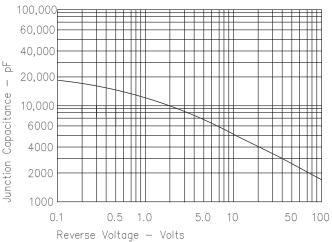


Figure 4

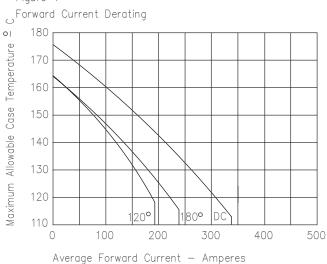


Figure 2 Typical Reverse Characteristics

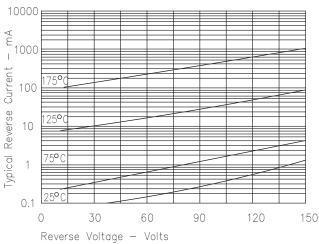
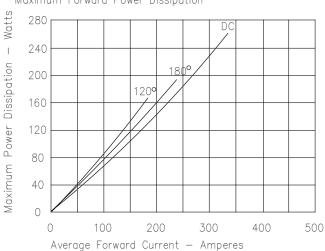


Figure 5 Maximum Forward Power Dissipation





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